

ABSTRACT

There is provided a circuit board including a first and a second circuit substrate located with a spacing, on which a first and a second conductor pad are provided respectively; and a

5 connection substrate including a first and a second conductor post projecting from one or the other side; the connection substrate being disposed so as to cover a portion of the first and the second circuit substrate, and bridged therebetween; the first conductor post and the first conductor pad, as well as the second conductor

10 post and the second conductor pad, being disposed so as to oppose each other; the circuit board also including a connector portion to be formed upon melting a metal coating layer, formed in advance on a surface of at least one of the first conductor post and the first conductor pad, and on a surface of at least one of the second

15 conductor post and the second conductor pad; the first and the second circuit substrate and the connection substrate being electrically connected through the connector portion.